ALPHA & OMEGA SEMICONDUCTOR

AO7800
Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

The AO7800 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V, in the small SOT363 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters.It is ESD protected.

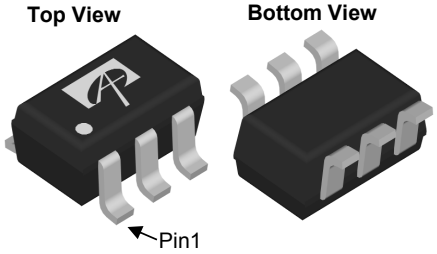
Features

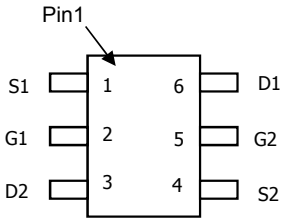
V_{DS} (V) = 20V
I_D = 0.9 A (V_{GS} = 4.5V)

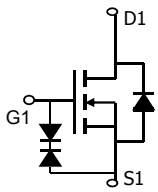
$R_{DS(ON)}$ < 300mΩ (V_{GS} = 4.5V)
$R_{DS(ON)}$ < 350mΩ (V_{GS} = 2.5V)
$R_{DS(ON)}$ < 450mΩ (V_{GS} = 1.8V)

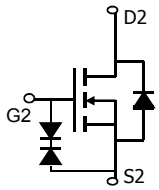
Green Product

SC70-6L (SOT-363)









Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	±8	V
Continuous Drain Current [A]	T_A=25°C	I_D	0.9	A
	T_A=70°C		0.7	
Pulsed Drain Current [B]		I_{DM}	5	
Power Dissipation [A]	T_A=25°C	P_D	0.9	W
	T_A=70°C		0.6	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	120	145	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		156	190	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	130	150	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	20			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=16V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±8V			25	µA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	0.5	0.75	0.9	V
$I_{D(ON)}$	On state drain current	V_{GS}=4.5V, V_{DS}=5V	5			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=4.5V, I_D=0.9A		181	300	mΩ
		T_J=125°C		253	350	
		V_{GS}=2.5V, I_D=0.75A		237	350	mΩ
		V_{GS}=1.8V, I_D=0.7A		317	450	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=0.8A		2.6		S
V_{SD}	Diode Forward Voltage	I_S=0.5A,V_{GS}=0V		0.69	1	V
I_S	Maximum Body-Diode Continuous Current				0.4	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=10V, f=1MHz		101	120	pF
C_{oss}	Output Capacitance			17		pF
C_{rss}	Reverse Transfer Capacitance			14		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		3	4	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=4.5V, V_{DS}=10V, I_D=0.8A		1.57	1.9	nC
Q_{gs}	Gate Source Charge			0.13		nC
Q_{gd}	Gate Drain Charge			0.36		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=5V, V_{DS}=10V, R_L=12.5Ω, R_{GEN}=6Ω		3.2		ns
t_r	Turn-On Rise Time			4		ns
$t_{D(off)}$	Turn-Off DelayTime			15.5		ns
t_f	Turn-Off Fall Time			2.4		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=0.8A, dI/dt=100A/µs		6.7	8.1	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=0.8A, dI/dt=100A/µs		1.6		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.
B: Repetitive rating, pulse width limited by junction temperature.
C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.
D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 µs pulses, duty cycle 0.5% max.
E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

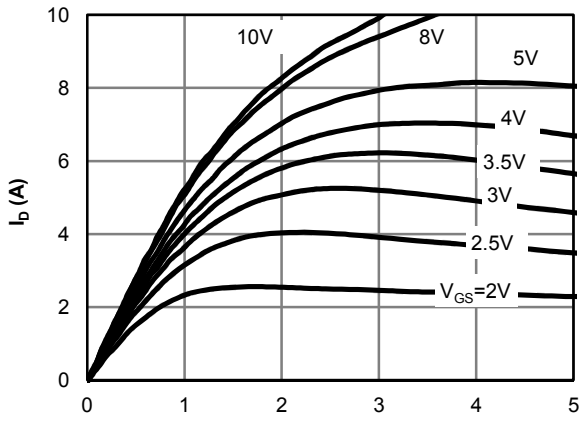


Fig 1: On-Region Characteristics

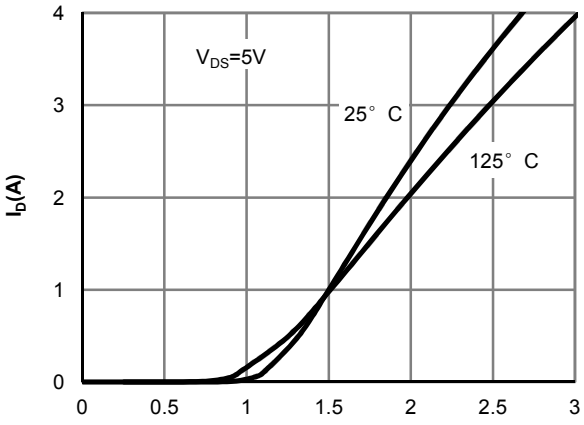


Figure 2: Transfer Characteristics

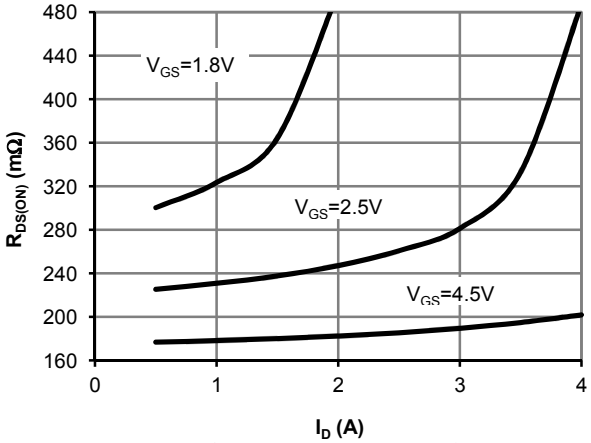


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

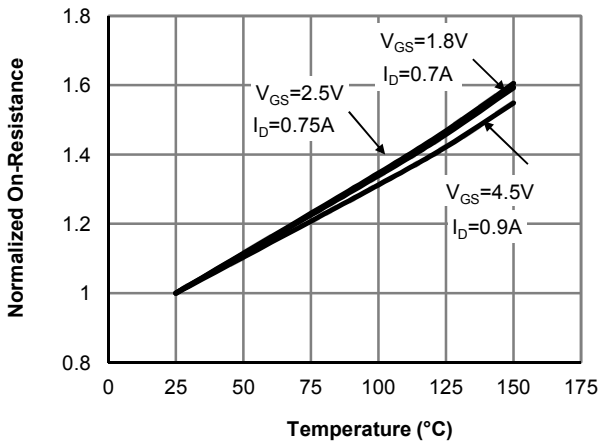


Figure 4: On-Resistance vs. Junction Temperature

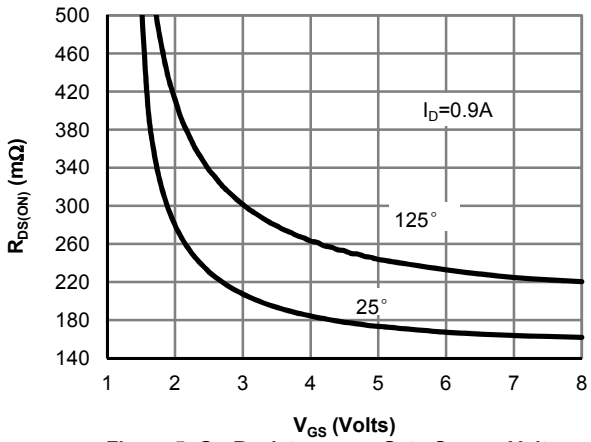


Figure 5: On-Resistance vs. Gate-Source Voltage

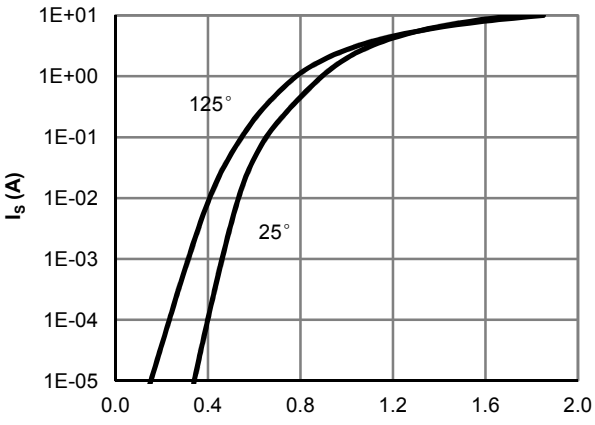


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

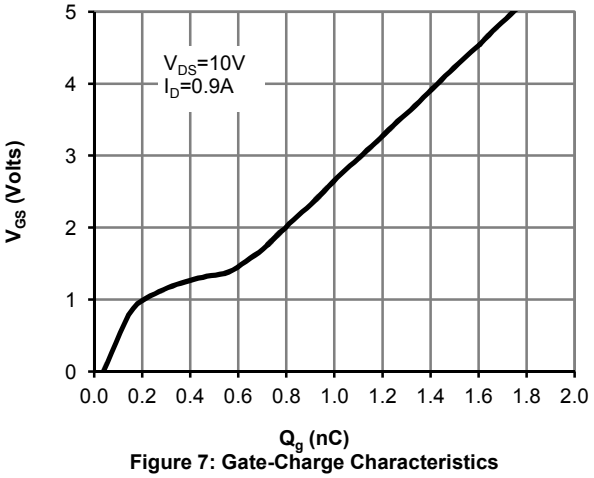


Figure 7: Gate-Charge Characteristics

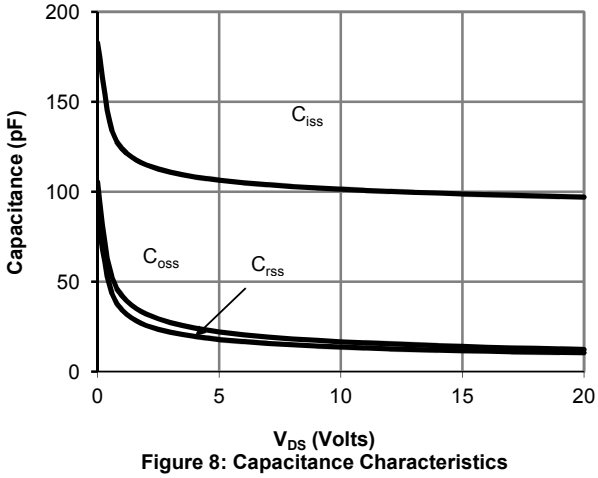


Figure 8: Capacitance Characteristics

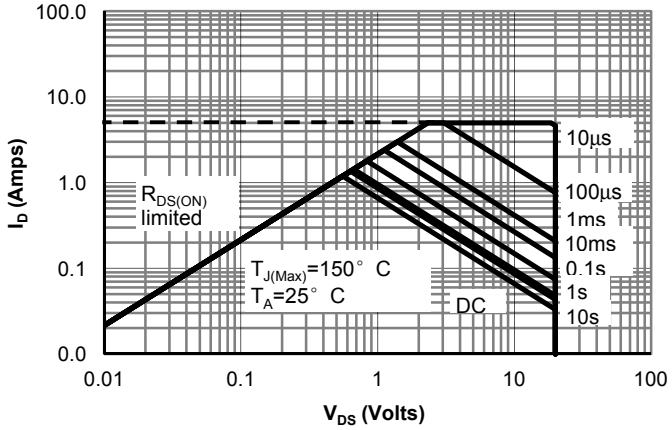


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

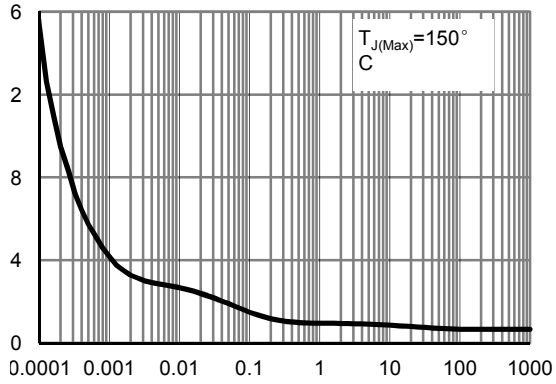


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

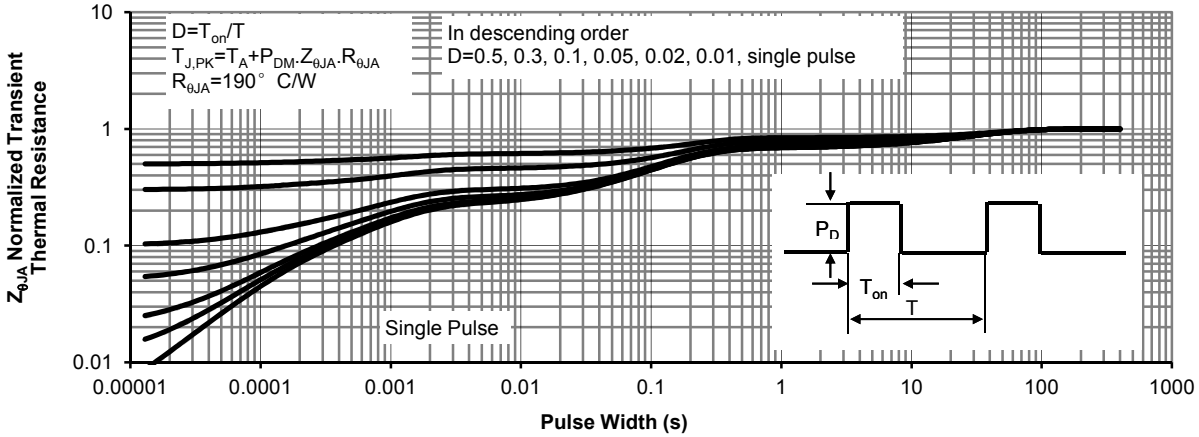
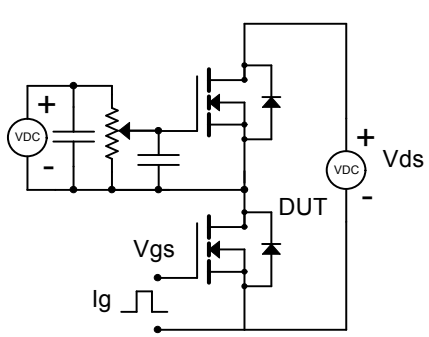
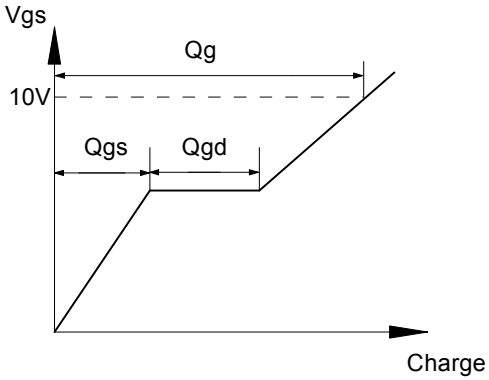


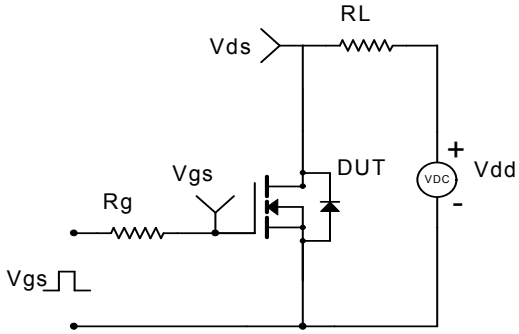
Figure 11: Normalized Maximum Transient Thermal Impedance

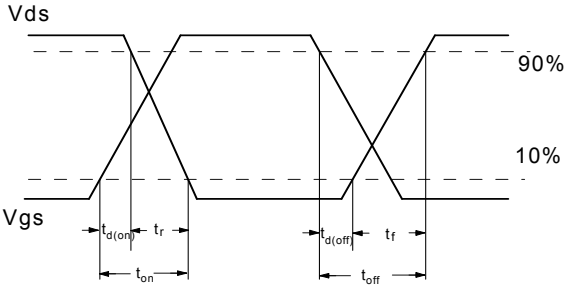
Gate Charge Test Circuit & Waveform





Resistive Switching Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms